

SPECIFICATION CSM28B2CZ

PACKAGE OUTLINES 5.60[0.221] RECOMMENDED PAD LAYOUT 2.15[0.085*] 6.9 [0.272"] + 2.4000.095°J ø1.8 [ø0.071*] 3.9 [0.154"] 4.60 [0.1811] -0.20 [0.008°] 80 [0.071*] CATHODE **+**0.80 [0.032°] Notes: 1. All dimensions are in millimeters (inches). 2. Tolerance is \pm 0.25mm (0.01") unless otherwised noted. 3. Specifications are subject to change without notice.

Part Number	Chip Material	Color of Emission	Lens Type	Viewing Angle	
CSM28B2CZ	InGaN	Blue	Water Clear	20°	





ABSOLUTE MAXIMUM RATINGS

(TA=25°C)

Parameter	Symbol	Max Rating	Unit	
Forward Current	lF	30	mA	
Reverse Current @ 5V	lr	10	μΑ	
Power Dissipation	Pd	114	mW	
Operating Temperature Range	Тор	-40~+85	°C	
Storage Temperature Range	Тѕтс	-40~+85	°C	
Peak Pulsing Current (1/10 duty f = 10KHz)	lfp	125	mA	
Soldering Temperature	Tsol	Max 260°C for 5 sec Max		

OPTICAL-ELECTRICAL CHARACTERISTICS

(TA=25°C)

Darameter	Symbol	Toot Condition	Value			Lloit
Parameter		Test Condition	Min	Тур	Max	Unit
Luminous Intensity	lv	IF = 20mA	1	1500	1	mcd
Forward Voltage	VF	IF = 20mA	-	3.3	3.8	V
Reverse Leakage Current	lr	V _R = 5V	-	-	10	μΑ
Viewing Angle at 50% Iv	201/2	IF = 20mA	-	20	-	Deg
Dominant Wavelength	λ D	IF = 20mA	ı	470	ı	nm

^{*}Tolerance of viewing angle: -10 / +5 deg.



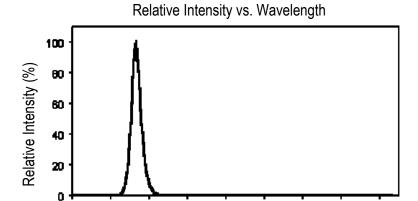


OPTICAL CHARACTERISTIC CURVES

300

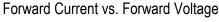
400

500



Wavelength (nm)

600



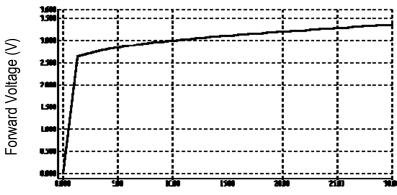
700

600

900

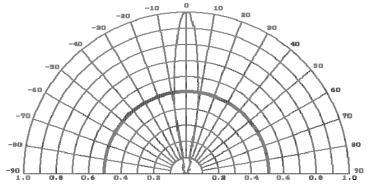
1000

1100



Forward Current (mA)

Directive Characteristics

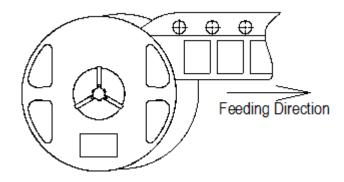


RoHS Compliant

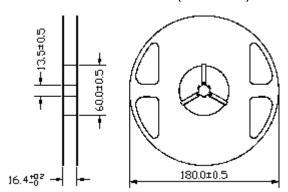


PACKAGING SPECIFICATION

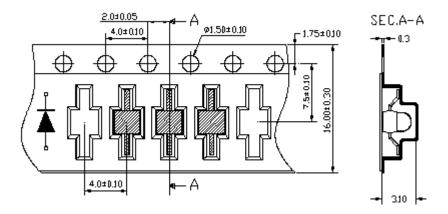
Feeding Direction



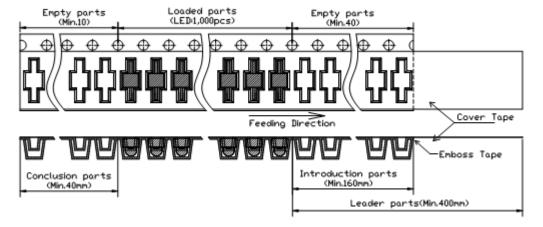
Dimensions of Reel (Unit: mm)



Dimensions of Tape (Unit: mm)



Arrangement of Tape



Notes:

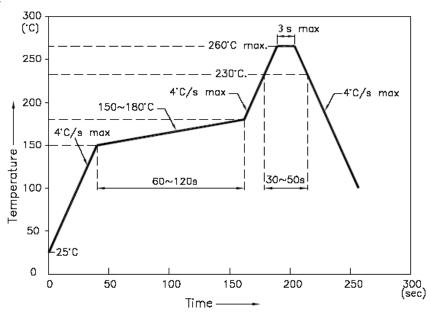
- 1. Empty component pockets are sealed with top cover tape;
- 2. The maximum number of missing lamp is two;
- 3. The cathode is oriented towards the tape sprocket hole;
- 4. 1,000 pcs/Reel





SOLDERING CONDITIONS

Reflow Temp/Time



Notes:

- 1. We recommend the reflow temperature 245°C (± 5 °C). The maximum soldering temperature should be limited to 260°C.
- 2. Don't cause stress to the epoxy resin while it is exposed to high temperature.
- 3. Number of reflow process should be 2 times or less.
- Soldering Iron

Basic spec is ≤ 5 sec when 260°C. If temperature is higher, time should be shorter ($\pm 10^{\circ}\text{C} \rightarrow -1\text{sec}$). Power dissipation of iron should be smaller than 20W and temperature should be controllable. Surface temperature of the device should be under 230°C.